PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCI No.	CRP/19/11478
1.3 Title of PCI	PRODUCT ALERT / Early Notification - DISCONTINUATION OF CURRENT MOLD COMPOUNDS (SAMSUNG SDI) FOR THROUGH HOLE PACKAGES
1.4 Product Category	Refer to FG list
1.5 Issue date	2019-04-08

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	FRANK SCHIFANO
2.1.2 Phone	+1 5148333778
2.1.3 Email	frank.schifano@st.com
2.2 Change responsibility	
2.2.1 Process Owner	Chiara ZACCHERINI
2.1.2 Corporate Quality Manager	Gerard PETIT

3. Change

3.1 Category	**3.2 Type of change**	**3.3 Manufacturing Location**
Materials	New direct material part number (same supplier, different supplier or new supplier), Mold compound	Several locations

4. Description of change

	Old	**New**
4.1 Description	Samsung SDI product termination of the following references of molding compound for through hole packages SG8200DTA SG8200DTB / 1 SG-8100G / GS / GSA SI-7200DXC SG8100GSP SI-7200DX2 ST-7100HF	Replacement of current mold compounds with alternative material. ST is already proceeding with new resins evaluation and qualification, to guarantee adequate products continuity.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Product Alert / Early Notification The change will be notified to customers by PCN sent by product divisions from Q2 2019 depending on the products and packages families.	

5. Reason / motivation for change

5.1 Motivation	Replacement of current mold compounds with alternative material. ST is already proceeding with new resins evaluation and qualification, to guarantee adequate products continuity.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	Not applicable at this stage

7. Timing / schedule

7.1 Date of qualification results	2019-04-05
7.2 Intended start of delivery	2019-04-05
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation

8.1 Description	

8.2 Qualification report and qualification results	In progress	**Issue Date**	

9. Attachments (additional documentations)

11478 Public product.pdf
11478 Early notification draft v4.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	STE53NC50	
	STP100N8F6	
	STPS160H100TV	
	STPS200170TV1	
	STPS30L30CT	
	STTH12012TV1	
	T835T-8T	
	TS110-8A1-AP	

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